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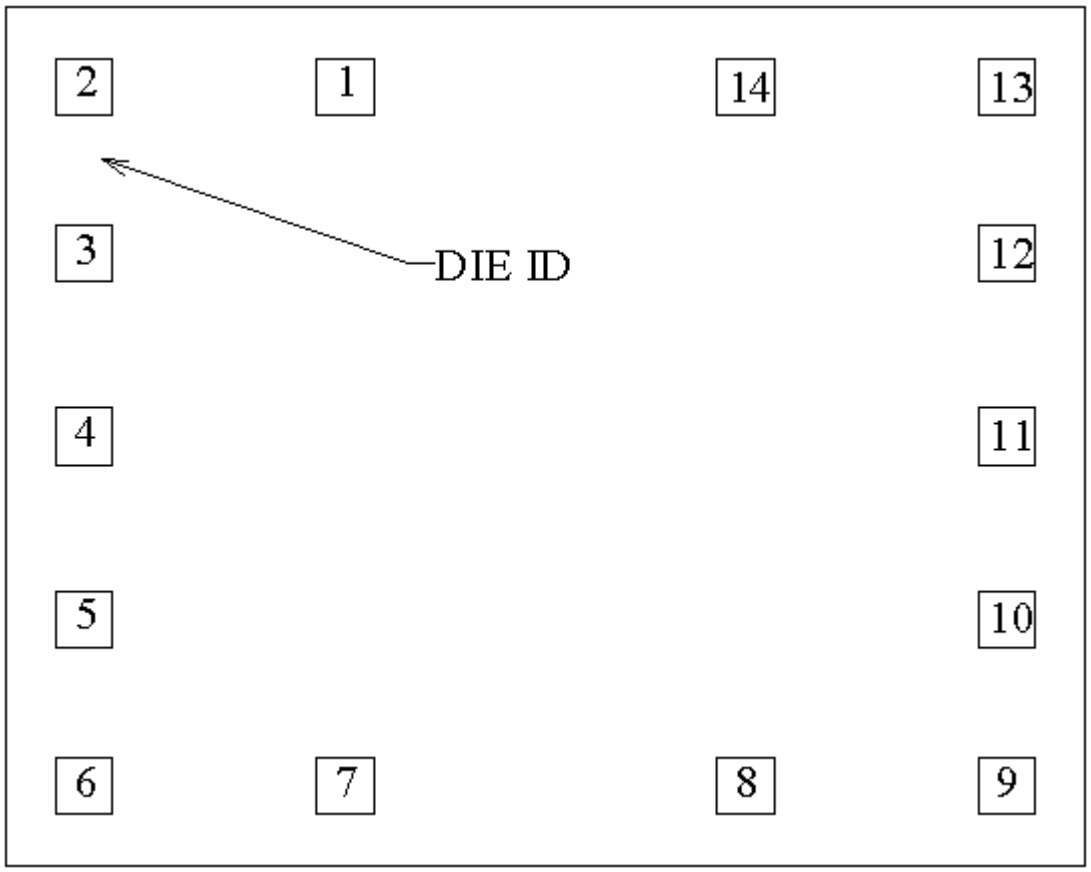
DPBU
Die Datasheet

LM148 MD8 MCD2660A
SERIES QUAD 741 OP AMP

August 06,2007

DIE LAYOUT (D-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM148	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1727µm x 1372µm 68.0mils x 54.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	266µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (D -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUTPUT 1	1	-320	559	91	x	91
INPUT 1-	2	-737	559	91	x	91
INPUT 1+	3	-737	292	91	x	91
V+	4	-737	0	91	x	91
INPUT 2+	5	-737	-292	91	x	91
INPUT 2-	6	-737	-559	91	x	91
OUTPUT 2	7	-320	-559	91	x	91
OUTPUT 3	8	320	-559	91	x	91
INPUT 3-	9	737	-559	91	x	91
INPUT 3+	10	737	-292	91	x	91
V-	11	737	0	91	x	91
INPUT 4+	12	737	292	91	x	91
INPUT 4-	13	737	559	91	x	91
OUTPUT 4	14	320	559	91	x	91

Notes

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